

## TDS

# SiO<sub>2</sub> FUSED SILICA SUBSTRATES

Fused silica is a widely used material with high chemical purity, good thermal characteristics and excellent homogeneity. Very good thermal expansion characteristic is an outstanding feature of fused silica. Fused silica is primarily used in wider thermal application. Fused silica includes UV grade and IR grade.

- Typical index Homogeneity :  $< 8 \times 10^{-6}$
- Thermal Expansion coefficient :  $0.58 \times 10^{-6}/K$  (0°C to 200°C)
- Density :  $2.201 \text{ g/cm}^3$



There are mainly three types of fused silica, NEGS1, NEGS2, NEGS3, they are used for different applications. Please refer to the table below for details.

Properties			
	NEGS1	NEGS2	NEGS3
<b>Maximum size</b>	< Ø 200 mm	< Ø 300 mm	< Ø 200 mm
<b>Transmission range (Medium transmission ratio)</b>	0.17~2.10µm (Tavg >90%)	0.26~2.10µm (Tavg >85%)	0.185~3.50µm (Tavg >85%)
<b>OH-Content</b>	1200 ppm	150 ppm	5 ppm
<b>Fluorescence (ex 254 nm)</b>	Virtually free	Strong v-b	Strong V-B
<b>Impurity Content</b>	5 ppm	20-40 ppm	40-50 ppm
<b>Birefringence Constant</b>	2-4 nm/cm	4-6 nm/cm	4-10 nm/cm
<b>Melting method</b>	Synthetic CVD	Oxy-hydrogen melting	Electrical melting
<b>Applications</b>	Laser substrate : window, lens, prism, mirror..	Semiconductor and high temperature	IR & UV substrate

**NEGS1** is mainly used for optics operating in the UV and the visible wavelength range. It is free of bubbles and inclusions. It is equivalent to Suprasil 1 & 2 and Corning 7980.

**NEGS2** is mainly used as mirror substrate, as it has tiny bubbles inside. It is equivalent to Homosil 1, 2 & 3.

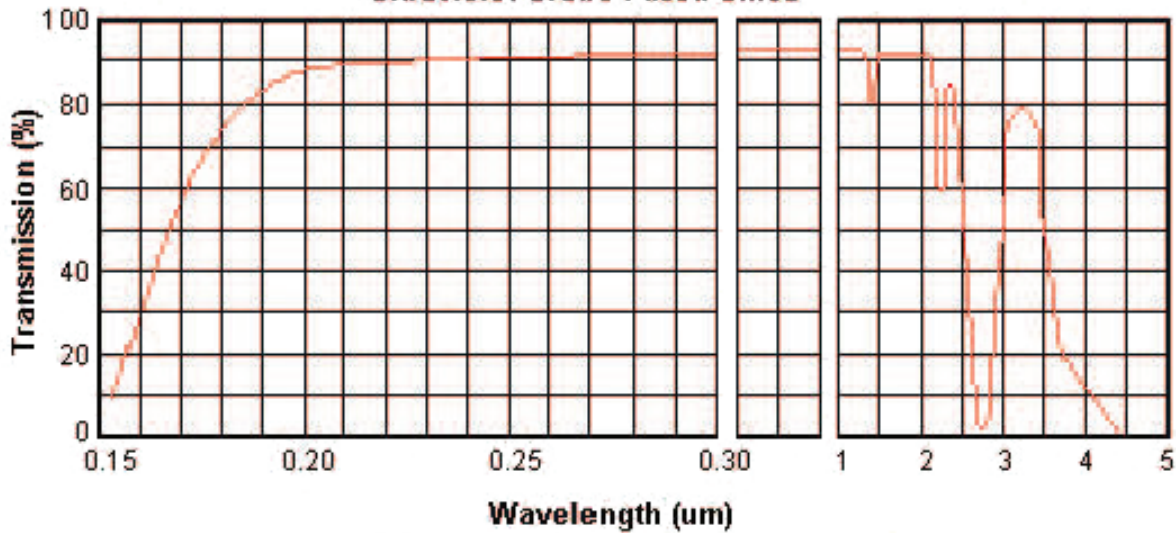
**NEGS3** is transparent in the ultraviolet, visible and infrared spectral regions, but it has many bubbles inside. It is equivalent to Suprasil 300.

Density		2.20 g/cm <sup>3</sup>	
Abbe Constant		67.6	
Refractive Index (nd) at 588 nm		1.4586	
Wavelength (µm)	Refractive index	Wavelength (µm)	Refractive index
0.200	1.55051	1.000	1.45042
0.220	1.52845	1.064	1.44962
0.250	1.50745	1.100	1.44920
0.300	1.48779	1.200	1.44805
0.320	1.48274	1.300	1.44692
0.360	1.47529	1.500	1.44462
0.400	1.47012	1.600	1.44342
0.450	1.46557	1.700	1.44217
0.488	1.46302	1.800	1.44087
0.500	1.46233	1.900	1.43951
0.550	1.46008	2.000	1.43809
0.588	1.45860	2.200	1.43501
0.600	1.45804	2.400	1.43163
0.633	1.45702	2.600	1.42789
0.650	1.45653	2.800	1.42377
0.700	1.45529	3.000	1.41925
0.750	1.45424	3.200	1.41427
0.800	1.45332	3.370	1.40990
0.850	1.45250	3.507	1.40566
0.900	1.45175	3.707	1.39936

<b>Hardness</b>	5.5 - 6.5 Mohs' Scale 570 KHN 100
<b>Design Tensile Strenght</b>	$4.8 \times 10^7$ Pa (N/mm <sup>2</sup> ) (7000 psi)
<b>Design Compressive Strenght</b>	Greater than $1.1 \times 10^9$ Pa (160,000 psi)
<b>Bulk Modulus</b>	$3.7 \times 10^{10}$ Pa ( $5.3 \times 10^6$ psi)
<b>Rigidity Modulus</b>	$3.1 \times 10^{10}$ Pa ( $4.5 \times 10^6$ psi)
<b>Young's Modulus</b>	$7.2 \times 10^{10}$ Pa ( $10.5 \times 10^6$ psi)
<b>Poisson's Ratio</b>	0.17
<b>Coefficient of Thermal Expansion</b>	$5.5 \times 10^{-7}$ cm/cm.°C (20°C-320°C)
<b>Thermal Conductivity</b>	1.4 W/m.°C
<b>Specific Heat</b>	670 J/kg.°C
<b>Softening Point</b>	1683 °C
<b>Annealing Point</b>	1215 °C
<b>Strain Point</b>	1120 °C
<b>Electrical Receptivity</b>	$7 \times 10^7$ ohm.cm (350 °C)
<b>Dielectric Properties (20 °C and 1 MHz)</b> Constant Strenght Loss Loss Factor Factor Dissipation	3.75 $5.10^7$ V/m Less than $4 \times 10^{-4}$ Less than $1 \times 10^{-4}$
<b>Velocity of Sound-Shear Wave</b>	$3.75 \times 10^3$ m/s
<b>Velocity of Sound/Compression Wave</b>	$5.90 \times 10^3$ m/s
<b>Sonic Attenuation</b>	Less than 11 db/m MHz
<b>Permeability Constants (cm<sup>3</sup>mm/cm<sup>2</sup>sec cm of Hg)</b> Helium Hydrogen Deuterium Neon	(700 °C) $210 \times 10^{-10}$ $21 \times 10^{-10}$ $17 \times 10^{-10}$ $9.5 \times 10^{-17}$
<b>Chemical stability (except hydrofluoric)</b>	High resistance to water and acids

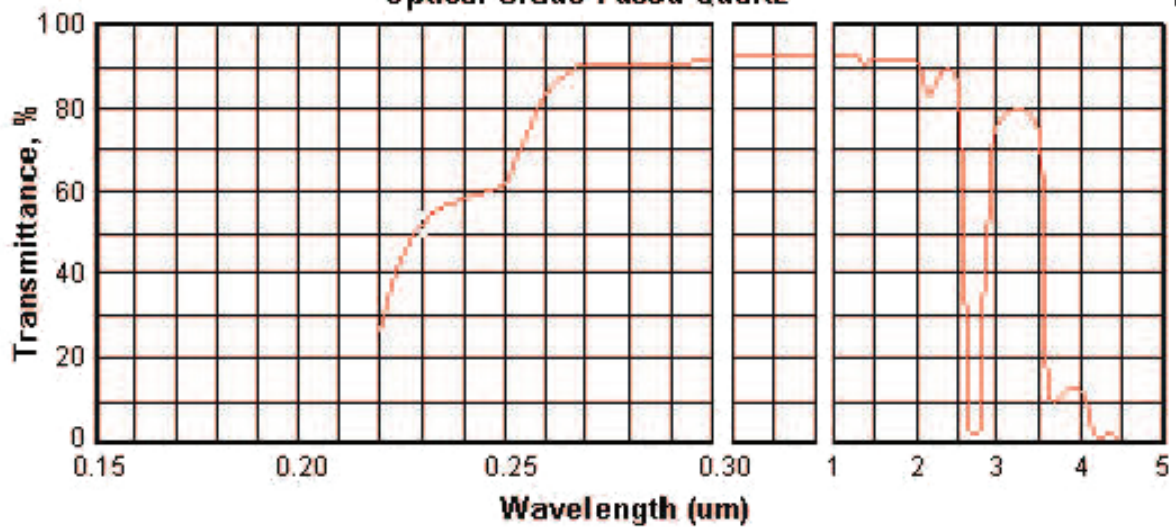
## Ultraviolet Grade Fused Silica

NEGS1



## Optical Grade Fused Quartz

NEGS2



## Full Spectrum Fused Silica

NEGS3

